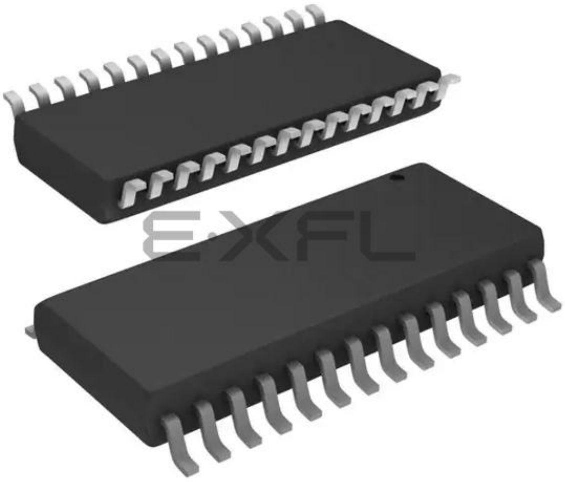

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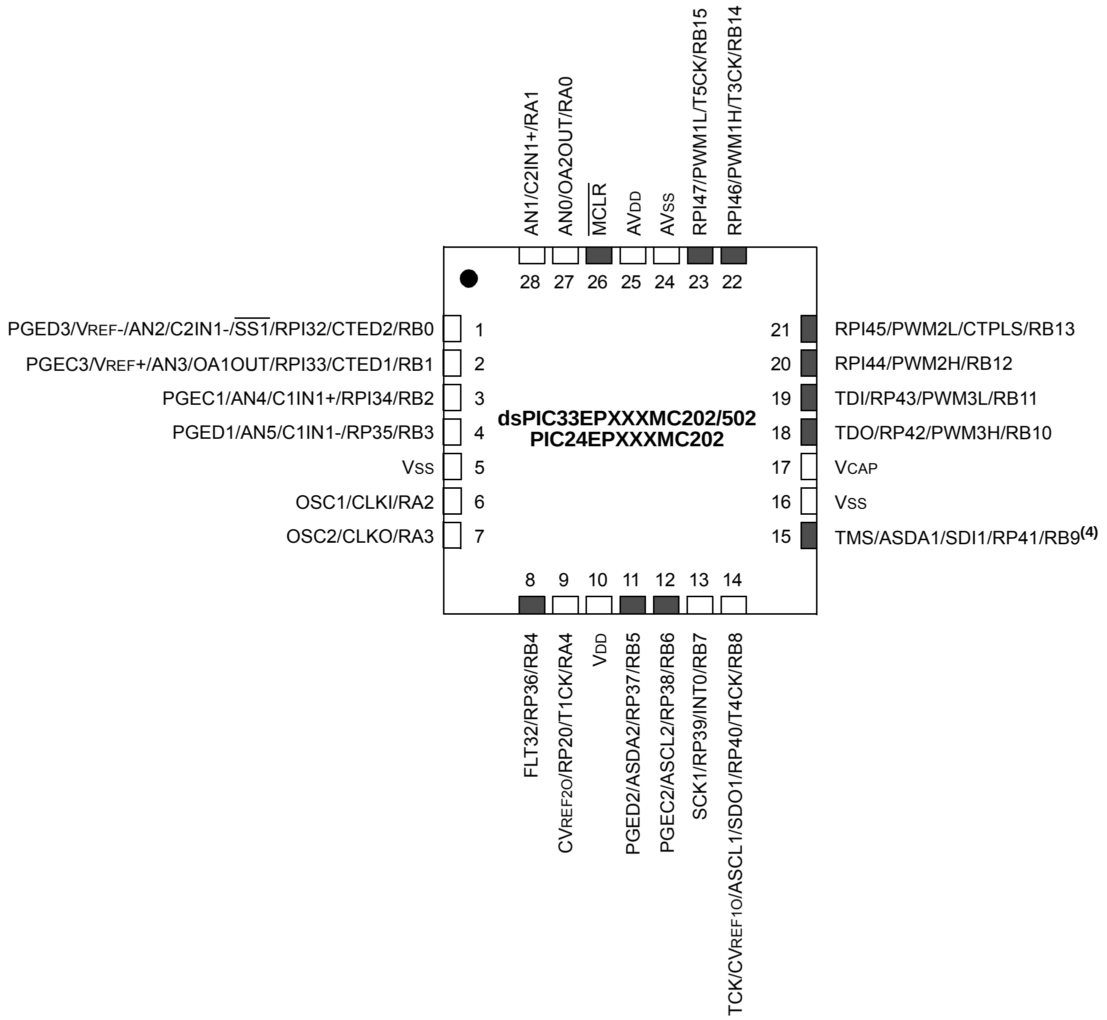
Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	PIC
Core Size	16-Bit
Speed	70 MIPs
Connectivity	I²C, IrDA, LINbus, QEI, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, DMA, Motor Control PWM, POR, PWM, WDT
Number of I/O	21
Program Memory Size	64KB (22K x 24)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	4K x 16
Voltage - Supply (Vcc/Vdd)	3V ~ 3.6V
Data Converters	A/D 6x10b/12b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	28-SOIC (0.295", 7.50mm Width)
Supplier Device Package	28-SOIC
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic24ep64mc202t-i-so

Pin Diagrams (Continued)

28-Pin QFN-S(1,2,3)

■ = Pins are up to 5V tolerant



Note 1: The RPn/RPIn pins can be used by any remappable peripheral with some limitation. See **Section 11.4 “Peripheral Pin Select (PPS)”** for available peripherals and for information on limitations.

2: Every I/O port pin (RAx-RGx) can be used as a Change Notification pin (CNAx-CNGx). See **Section 11.0 “I/O Ports”** for more information.

3: The metal pad at the bottom of the device is not connected to any pins and is recommended to be connected to VSS externally.

4: There is an internal pull-up resistor connected to the TMS pin when the JTAG interface is active. See the JTAGEN bit field in Table 27-2.

1.0 DEVICE OVERVIEW

Note 1: This data sheet summarizes the features of the dsPIC33EPXXXGP50X, dsPIC33EPXXXMC20X/50X and PIC24EPXXXGP/MC20X families of devices. It is not intended to be a comprehensive resource. To complement the information in this data sheet, refer to the related section of the "*dsPIC33/PIC24 Family Reference Manual*", which is available from the Microchip web site (www.microchip.com)

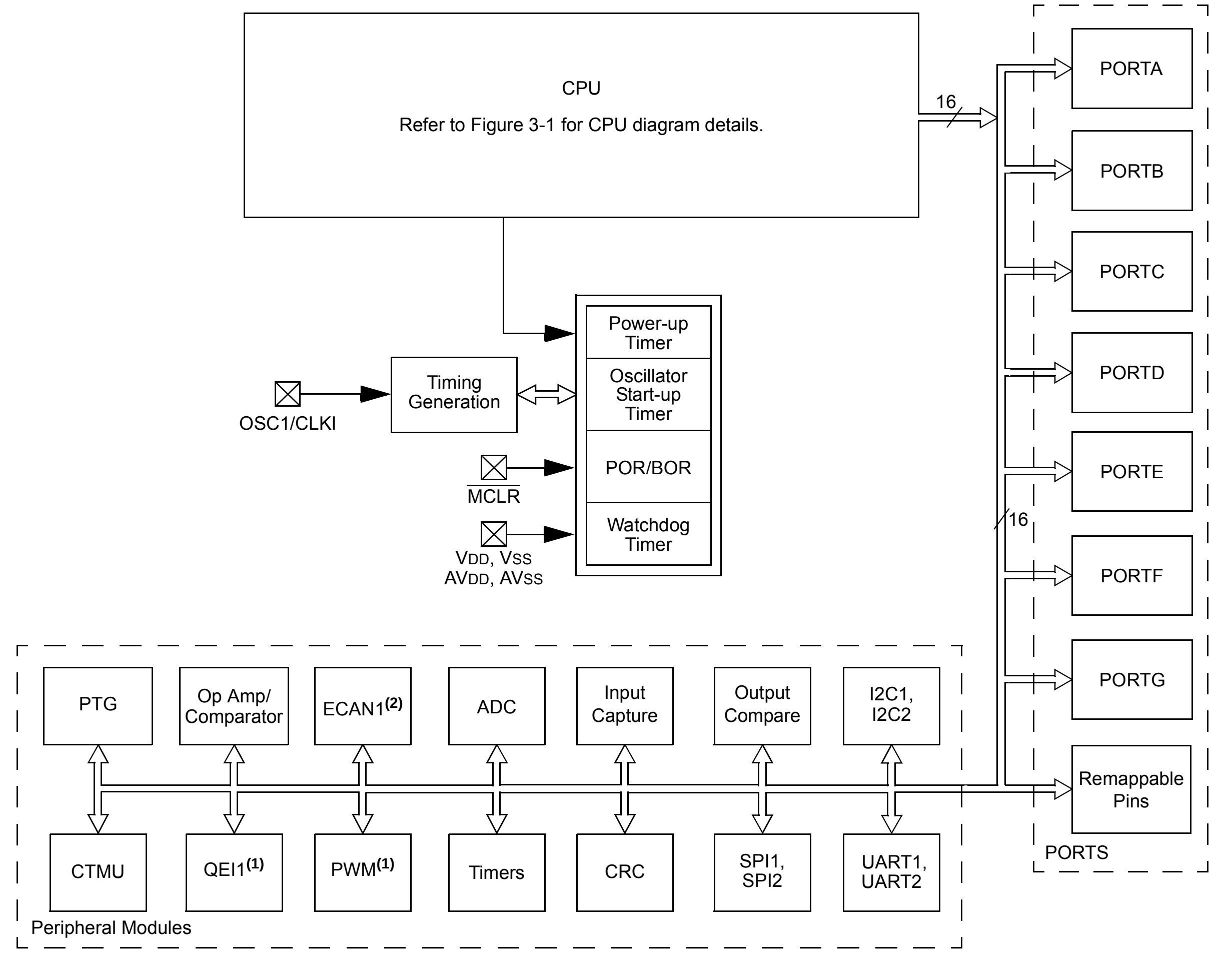
2: Some registers and associated bits described in this section may not be available on all devices. Refer to **Section 4.0 "Memory Organization"** in this data sheet for device-specific register and bit information.

This document contains device-specific information for the dsPIC33EPXXXGP50X, dsPIC33EPXXXMC20X/50X and PIC24EPXXXGP/MC20X Digital Signal Controller (DSC) and Microcontroller (MCU) devices.

dsPIC33EPXXXMC20X/50X and dsPIC33EPXXXGP50X devices contain extensive Digital Signal Processor (DSP) functionality with a high-performance, 16-bit MCU architecture.

Figure 1-1 shows a general block diagram of the core and peripheral modules. Table 1-1 lists the functions of the various pins shown in the pinout diagrams.

FIGURE 1-1: dsPIC33EPXXXGP50X, dsPIC33EPXXXMC20X/50X AND PIC24EPXXXGP/MC20X BLOCK DIAGRAM



Note 1: This feature or peripheral is only available on dsPIC33EPXXXMC20X/50X and PIC24EPXXXMC20X devices.

2: This feature or peripheral is only available on dsPIC33EPXXXGP/MC50X devices.

4.2.5 X AND Y DATA SPACES

The dsPIC33EPXXXMC20X/50X and dsPIC33EPXXXGP50X core has two Data Spaces, X and Y. These Data Spaces can be considered either separate (for some DSP instructions) or as one unified linear address range (for MCU instructions). The Data Spaces are accessed using two Address Generation Units (AGUs) and separate data paths. This feature allows certain instructions to concurrently fetch two words from RAM, thereby enabling efficient execution of DSP algorithms, such as Finite Impulse Response (FIR) filtering and Fast Fourier Transform (FFT).

The X Data Space is used by all instructions and supports all addressing modes. X Data Space has separate read and write data buses. The X read data bus is the read data path for all instructions that view Data Space as combined X and Y address space. It is also the X data prefetch path for the dual operand DSP instructions (`MAC` class).

The Y Data Space is used in concert with the X Data Space by the `MAC` class of instructions (`CLR`, `ED`, `EDAC`, `MAC`, `MOVSAC`, `MPY`, `MPY.N` and `MSC`) to provide two concurrent data read paths.

Both the X and Y Data Spaces support Modulo Addressing mode for all instructions, subject to addressing mode restrictions. Bit-Reversed Addressing mode is only supported for writes to X Data Space. Modulo Addressing and Bit-Reversed Addressing are not present in PIC24EPXXXGP/MC20X devices.

All data memory writes, including in DSP instructions, view Data Space as combined X and Y address space. The boundary between the X and Y Data Spaces is device-dependent and is not user-programmable.

4.3 Memory Resources

Many useful resources are provided on the main product page of the Microchip web site for the devices listed in this data sheet. This product page, which can be accessed using this link, contains the latest updates and additional information.

Note: In the event you are not able to access the product page using the link above, enter this URL in your browser:
http://www.microchip.com/wwwproducts/Devices.aspx?dDocName=en555464

4.3.1 KEY RESOURCES

- **"Program Memory"** (DS70613) in the *"dsPIC33/PIC24 Family Reference Manual"*
- Code Samples
- Application Notes
- Software Libraries
- Webinars
- All Related *"dsPIC33/PIC24 Family Reference Manual"* Sections
- Development Tools

4.5 Instruction Addressing Modes

The addressing modes shown in Table 4-63 form the basis of the addressing modes optimized to support the specific features of individual instructions. The addressing modes provided in the `MAC` class of instructions differ from those in the other instruction types.

4.5.1 FILE REGISTER INSTRUCTIONS

Most file register instructions use a 13-bit address field (f) to directly address data present in the first 8192 bytes of data memory (Near Data Space). Most file register instructions employ a working register, W0, which is denoted as WREG in these instructions. The destination is typically either the same file register or WREG (with the exception of the `MUL` instruction), which writes the result to a register or register pair. The `MOV` instruction allows additional flexibility and can access the entire Data Space.

4.5.2 MCU INSTRUCTIONS

The three-operand MCU instructions are of the form:

`Operand 3 = Operand 1 <function> Operand 2`

where Operand 1 is always a working register (that is, the addressing mode can only be Register Direct), which is referred to as Wb. Operand 2 can be a W register fetched from data memory or a 5-bit literal. The result location can either be a W register or a data memory location. The following addressing modes are supported by MCU instructions:

- Register Direct
- Register Indirect
- Register Indirect Post-Modified
- Register Indirect Pre-Modified
- 5-Bit or 10-Bit Literal

Note: Not all instructions support all the addressing modes given above. Individual instructions can support different subsets of these addressing modes.

TABLE 4-63: FUNDAMENTAL ADDRESSING MODES SUPPORTED

Addressing Mode	Description
File Register Direct	The address of the file register is specified explicitly.
Register Direct	The contents of a register are accessed directly.
Register Indirect	The contents of Wn form the Effective Address (EA).
Register Indirect Post-Modified	The contents of Wn form the EA. Wn is post-modified (incremented or decremented) by a constant value.
Register Indirect Pre-Modified	Wn is pre-modified (incremented or decremented) by a signed constant value to form the EA.
Register Indirect with Register Offset (Register Indexed)	The sum of Wn and Wb forms the EA.
Register Indirect with Literal Offset	The sum of Wn and a literal forms the EA.

7.3 Interrupt Resources

Many useful resources are provided on the main product page of the Microchip web site for the devices listed in this data sheet. This product page, which can be accessed using this link, contains the latest updates and additional information.

Note: In the event you are not able to access the product page using the link above, enter this URL in your browser:
http://www.microchip.com/wwwproducts/Devices.aspx?dDocName=en555464

7.3.1 KEY RESOURCES

- **“Interrupts”** (DS70600) in the *“dsPIC33/PIC24 Family Reference Manual”*
- Code Samples
- Application Notes
- Software Libraries
- Webinars
- All Related *“dsPIC33/PIC24 Family Reference Manual”* Sections
- Development Tools

7.4 Interrupt Control and Status Registers

dsPIC33EPXXXGP50X, dsPIC33EPXXXMC20X/50X and PIC24EPXXXGP/MC20X devices implement the following registers for the interrupt controller:

- INTCON1
- INTCON2
- INTCON3
- INTCON4
- INTTREG

7.4.1 INTCON1 THROUGH INTCON4

Global interrupt control functions are controlled from INTCON1, INTCON2, INTCON3 and INTCON4.

INTCON1 contains the Interrupt Nesting Disable bit (NSTDIS), as well as the control and status flags for the processor trap sources.

The INTCON2 register controls external interrupt request signal behavior and also contains the Global Interrupt Enable bit (GIE).

INTCON3 contains the status flags for the DMA and DO stack overflow status trap sources.

The INTCON4 register contains the software generated hard trap status bit (SGHT).

7.4.2 IFSx

The IFSx registers maintain all of the interrupt request flags. Each source of interrupt has a status bit, which is set by the respective peripherals or external signal and is cleared via software.

7.4.3 IECx

The IECx registers maintain all of the interrupt enable bits. These control bits are used to individually enable interrupts from the peripherals or external signals.

7.4.4 IPCx

The IPCx registers are used to set the Interrupt Priority Level (IPL) for each source of interrupt. Each user interrupt source can be assigned to one of eight priority levels.

7.4.5 INTTREG

The INTTREG register contains the associated interrupt vector number and the new CPU Interrupt Priority Level, which are latched into the Vector Number bits (VECNUM<7:0>) and Interrupt Priority Level bits (ILR<3:0>) fields in the INTTREG register. The new Interrupt Priority Level is the priority of the pending interrupt.

The interrupt sources are assigned to the IFSx, IECx and IPCx registers in the same sequence as they are listed in Table 7-1. For example, the INT0 (External Interrupt 0) is shown as having Vector Number 8 and a natural order priority of 0. Thus, the INT0IF bit is found in IFS0<0>, the INT0IE bit in IEC0<0> and the INT0IP bits in the first position of IPC0 (IPC0<2:0>).

7.4.6 STATUS/CONTROL REGISTERS

Although these registers are not specifically part of the interrupt control hardware, two of the CPU Control registers contain bits that control interrupt functionality. For more information on these registers refer to **“CPU”** (DS70359) in the *“dsPIC33/PIC24 Family Reference Manual”*.

- The CPU STATUS Register, SR, contains the IPL<2:0> bits (SR<7:5>). These bits indicate the current CPU Interrupt Priority Level. The user software can change the current CPU Interrupt Priority Level by writing to the IPLx bits.
- The CORCON register contains the IPL3 bit which, together with IPL<2:0>, also indicates the current CPU priority level. IPL3 is a read-only bit so that trap events cannot be masked by the user software.

All Interrupt registers are described in Register 7-3 through Register 7-7 in the following pages.

REGISTER 8-13: DMALCA: DMA LAST CHANNEL ACTIVE STATUS REGISTER

U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
—	—	—	—	—	—	—	—
bit 15							bit 8

U-0	U-0	U-0	U-0	R-1	R-1	R-1	R-1
—	—	—	—	LSTCH<3:0>			
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15-4	**Unimplemented:** Read as ‘`0`’
bit 3-0	**LSTCH<3:0>:** Last DMAC Channel Active Status bits `1111` = No DMA transfer has occurred since system Reset `1110` = Reserved • • • `0100` = Reserved `0011` = Last data transfer was handled by Channel 3 `0010` = Last data transfer was handled by Channel 2 `0001` = Last data transfer was handled by Channel 1 `0000` = Last data transfer was handled by Channel 0

REGISTER 15-1: OCxCON1: OUTPUT COMPARE x CONTROL REGISTER 1 (CONTINUED)

bit 3 **TRIGMODE:** Trigger Status Mode Select bit

`1` = TRIGSTAT (OCxCON2<6>) is cleared when OCxRS = OCxTMR or in software
`0` = TRIGSTAT is cleared only by software

bit 2-0 **OCM<2:0>:** Output Compare x Mode Select bits

`111` = Center-Aligned PWM mode: Output set high when OCxTMR = OCxR and set low when OCxTMR = OCxRS[1]
`110` = Edge-Aligned PWM mode: Output set high when OCxTMR = `0` and set low when OCxTMR = OCxR[1]
`101` = Double Compare Continuous Pulse mode: Initializes OCx pin low, toggles OCx state continuously on alternate matches of OCxR and OCxRS
`100` = Double Compare Single-Shot mode: Initializes OCx pin low, toggles OCx state on matches of OCxR and OCxRS for one cycle
`011` = Single Compare mode: Compare event with OCxR, continuously toggles OCx pin
`010` = Single Compare Single-Shot mode: Initializes OCx pin high, compare event with OCxR, forces OCx pin low
`001` = Single Compare Single-Shot mode: Initializes OCx pin low, compare event with OCxR, forces OCx pin high
`000` = Output compare channel is disabled

Note 1: OCxR and OCxRS are double-buffered in PWM mode only.

2: Each Output Compare x module (OCx) has one PTG clock source. See **Section 24.0 “Peripheral Trigger Generator (PTG) Module”** for more information.
PTGO4 = OC1
PTGO5 = OC2
PTGO6 = OC3
PTGO7 = OC4

REGISTER 16-8: PDCx: PWMx GENERATOR DUTY CYCLE REGISTER

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
PDCx<15:8>							
bit 15							bit 8

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
PDCx<7:0>							
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15-0 **PDCx<15:0>:** PWMx Generator # Duty Cycle Value bits

REGISTER 16-9: PHASEx: PWMx PRIMARY PHASE-SHIFT REGISTER

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
PHASEx<15:8>							
bit 15							bit 8

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
PHASEx<7:0>							
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15-0 **PHASEx<15:0>:** PWMx Phase-Shift Value or Independent Time Base Period for the PWM Generator bits

Note 1: If ITB (PWMCONx<9>) = `0`, the following applies based on the mode of operation:
Complementary, Redundant and Push-Pull Output mode (PMOD<1:0> (IOCON<11:10>) = `00`, `01` or `10`),
PHASEx<15:0> = Phase-shift value for PWMxH and PWMxL outputs

2: If ITB (PWMCONx<9>) = `1`, the following applies based on the mode of operation:
Complementary, Redundant and Push-Pull Output mode (PMOD<1:0> (IOCONx<11:10>) = `00`, `01` or `10`),
PHASEx<15:0> = Independent time base period value for PWMxH and PWMxL

REGISTER 21-24: CxRXOVF1: ECANx RECEIVE BUFFER OVERFLOW REGISTER 1

R/C-0	R/C-0	R/C-0	R/C-0	R/C-0	R/C-0	R/C-0	R/C-0
RXOVF15	RXOVF14	RXOVF13	RXOVF12	RXOVF11	RXOVF10	RXOVF9	RXOVF8
bit 15							bit 8

R/C-0	R/C-0	R/C-0	R/C-0	R/C-0	R/C-0	R/C-0	R/C-0
RXOVF7	RXOVF6	RXOVF5	RXOVF4	RXOVF3	RXOVF2	RXOVF1	RXOVF0
bit 7							bit 0

Legend:	C = Writable bit, but only ‘0’ can be written to clear the bit		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15-0 **RXOVF<15:0>:** Receive Buffer n Overflow bits

`1` = Module attempted to write to a full buffer (set by module)
`0` = No overflow condition (cleared by user software)

REGISTER 21-25: CxRXOVF2: ECANx RECEIVE BUFFER OVERFLOW REGISTER 2

R/C-0	R/C-0	R/C-0	R/C-0	R/C-0	R/C-0	R/C-0	R/C-0
RXOVF31	RXOVF30	RXOVF29	RXOVF28	RXOVF27	RXOVF26	RXOVF25	RXOVF24
bit 15							bit 8

R/C-0	R/C-0	R/C-0	R/C-0	R/C-0	R/C-0	R/C-0	R/C-0
RXOVF23	RXOVF22	RXOVF21	RXOVF20	RXOVF19	RXOVF18	RXOVF17	RXOVF16
bit 7							bit 0

Legend:	C = Writable bit, but only ‘0’ can be written to clear the bit		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15-0 **RXOVF<31:16>:** Receive Buffer n Overflow bits

`1` = Module attempted to write to a full buffer (set by module)
`0` = No overflow condition (cleared by user software)

23.4 ADC Control Registers

REGISTER 23-1: AD1CON1: ADC1 CONTROL REGISTER 1

R/W-0	U-0	R/W-0	R/W-0	U-0	R/W-0	R/W-0	R/W-0
ADON	—	ADSIDL	ADDMABM	—	AD12B	FORM1	FORM0
bit 15							bit 8

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0, HC, HS	R/C-0, HC, HS
SSRC2	SSRC1	SSRC0	SSRCG	SIMSAM	ASAM	SAMP	DONE[3]
bit 7							bit 0

Legend:	HC = Hardware Clearable bit	HS = Hardware Settable bit	C = Clearable bit
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15 **ADON:** ADC1 Operating Mode bit

`1` = ADC module is operating
`0` = ADC is off

bit 14 **Unimplemented:** Read as ‘`0`’

bit 13 **ADSIDL:** ADC1 Stop in Idle Mode bit

`1` = Discontinues module operation when device enters Idle mode
`0` = Continues module operation in Idle mode

bit 12 **ADDMABM:** DMA Buffer Build Mode bit

`1` = DMA buffers are written in the order of conversion; the module provides an address to the DMA channel that is the same as the address used for the non-DMA stand-alone buffer
`0` = DMA buffers are written in Scatter/Gather mode; the module provides a Scatter/Gather address to the DMA channel, based on the index of the analog input and the size of the DMA buffer.

bit 11 **Unimplemented:** Read as ‘`0`’

bit 10 **AD12B:** ADC1 10-Bit or 12-Bit Operation Mode bit

`1` = 12-bit, 1-channel ADC operation
`0` = 10-bit, 4-channel ADC operation

bit 9-8 **FORM<1:0>:** Data Output Format bits

For 10-Bit Operation:
`11` = Signed fractional (DOUT = `sddd dddd dd00 0000`, where `s` = .NOT.d<9>)
`10` = Fractional (DOUT = `dddd dddd dd00 0000`)
`01` = Signed integer (DOUT = `ssss sssd dddd dddd`, where `s` = .NOT.d<9>)
`00` = Integer (DOUT = `0000 00dd dddd dddd`)

For 12-Bit Operation:
`11` = Signed fractional (DOUT = `sddd dddd dddd 0000`, where `s` = .NOT.d<11>)
`10` = Fractional (DOUT = `dddd dddd dddd 0000`)
`01` = Signed integer (DOUT = `ssss sddd dddd dddd`, where `s` = .NOT.d<11>)
`00` = Integer (DOUT = `0000 dddd dddd dddd`)

Note 1: See **Section 24.0 “Peripheral Trigger Generator (PTG) Module”** for information on this selection.
2: This setting is available in dsPIC33EPXXXMC20X/50X and PIC24EPXXXMC20X devices only.
3: Do not clear the DONE bit in software if Auto-Sample is enabled (ASAM = `1`).

REGISTER 23-7: AD1CSSH: ADC1 INPUT SCAN SELECT REGISTER HIGH(1)

R/W-0	R/W-0	U-0	U-0	U-0	R/W-0	R/W-0	R/W-0
CSS31	CSS30	—	—	—	CSS26(2)	CSS25(2)	CSS24(2)
bit 15							bit 8

U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
—	—	—	—	—	—	—	—
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15	**CSS31:** ADC1 Input Scan Selection bit `1` = Selects CTMU capacitive and time measurement for input scan (Open) `0` = Skips CTMU capacitive and time measurement for input scan (Open)
bit 14	**CSS30:** ADC1 Input Scan Selection bit `1` = Selects CTMU on-chip temperature measurement for input scan (CTMU TEMP) `0` = Skips CTMU on-chip temperature measurement for input scan (CTMU TEMP)
bit 13-11	**Unimplemented:** Read as ‘`0`’
bit 10	**CSS26:** ADC1 Input Scan Selection bit(2) `1` = Selects OA3/AN6 for input scan `0` = Skips OA3/AN6 for input scan
bit 9	**CSS25:** ADC1 Input Scan Selection bit(2) `1` = Selects OA2/AN0 for input scan `0` = Skips OA2/AN0 for input scan
bit 8	**CSS24:** ADC1 Input Scan Selection bit(2) `1` = Selects OA1/AN3 for input scan `0` = Skips OA1/AN3 for input scan
bit 7-0	**Unimplemented:** Read as ‘`0`’

Note 1: All AD1CSSH bits can be selected by user software. However, inputs selected for scan, without a corresponding input on the device, convert VREFL.

2: The OAx input is used if the corresponding op amp is selected (OPMODE (CMxCON<10>) = `1`); otherwise, the ANx input is used.

TABLE 28-2: INSTRUCTION SET OVERVIEW (CONTINUED)

Base Instr #	Assembly Mnemonic	Assembly Syntax		Description	# of Words	# of Cycles(2)	Status Flags Affected
72	`SL`	`SL`	`f`	f = Left Shift f	1	1	C,N,OV,Z
		`SL`	`f,WREG`	WREG = Left Shift f	1	1	C,N,OV,Z
		`SL`	`Ws,Wd`	Wd = Left Shift Ws	1	1	C,N,OV,Z
		`SL`	`Wb,Wns,Wnd`	Wnd = Left Shift Wb by Wns	1	1	N,Z
		`SL`	`Wb,#lit5,Wnd`	Wnd = Left Shift Wb by lit5	1	1	N,Z
73	`SUB`	`SUB`	`Acc`(1)	Subtract Accumulators	1	1	OA,OB,OAB, SA,SB,SAB
		`SUB`	`f`	f = f – WREG	1	1	C,DC,N,OV,Z
		`SUB`	`f,WREG`	WREG = f – WREG	1	1	C,DC,N,OV,Z
		`SUB`	`#lit10,Wn`	Wn = Wn – lit10	1	1	C,DC,N,OV,Z
		`SUB`	`Wb,Ws,Wd`	Wd = Wb – Ws	1	1	C,DC,N,OV,Z
		`SUB`	`Wb,#lit5,Wd`	Wd = Wb – lit5	1	1	C,DC,N,OV,Z
74	`SUBB`	`SUBB`	`f`	f = f – WREG – $(\overline{C})$	1	1	C,DC,N,OV,Z
		`SUBB`	`f,WREG`	WREG = f – WREG – $(\overline{C})$	1	1	C,DC,N,OV,Z
		`SUBB`	`#lit10,Wn`	Wn = Wn – lit10 – $(\overline{C})$	1	1	C,DC,N,OV,Z
		`SUBB`	`Wb,Ws,Wd`	Wd = Wb – Ws – $(\overline{C})$	1	1	C,DC,N,OV,Z
		`SUBB`	`Wb,#lit5,Wd`	Wd = Wb – lit5 – $(\overline{C})$	1	1	C,DC,N,OV,Z
75	`SUBR`	`SUBR`	`f`	f = WREG – f	1	1	C,DC,N,OV,Z
		`SUBR`	`f,WREG`	WREG = WREG – f	1	1	C,DC,N,OV,Z
		`SUBR`	`Wb,Ws,Wd`	Wd = Ws – Wb	1	1	C,DC,N,OV,Z
		`SUBR`	`Wb,#lit5,Wd`	Wd = lit5 – Wb	1	1	C,DC,N,OV,Z
76	`SUBBR`	`SUBBR`	`f`	f = WREG – f – $(\overline{C})$	1	1	C,DC,N,OV,Z
		`SUBBR`	`f,WREG`	WREG = WREG – f – $(\overline{C})$	1	1	C,DC,N,OV,Z
		`SUBBR`	`Wb,Ws,Wd`	Wd = Ws – Wb – $(\overline{C})$	1	1	C,DC,N,OV,Z
		`SUBBR`	`Wb,#lit5,Wd`	Wd = lit5 – Wb – $(\overline{C})$	1	1	C,DC,N,OV,Z
77	`SWAP`	`SWAP.b`	`Wn`	Wn = nibble swap Wn	1	1	None
		`SWAP`	`Wn`	Wn = byte swap Wn	1	1	None
78	`TBLRDH`	`TBLRDH`	`Ws,Wd`	Read Prog<23:16> to Wd<7:0>	1	5	None
79	`TBLRDL`	`TBLRDL`	`Ws,Wd`	Read Prog<15:0> to Wd	1	5	None
80	`TBLWTH`	`TBLWTH`	`Ws,Wd`	Write Ws<7:0> to Prog<23:16>	1	2	None
81	`TBLWTL`	`TBLWTL`	`Ws,Wd`	Write Ws to Prog<15:0>	1	2	None
82	`ULNK`	`ULNK`		Unlink Frame Pointer	1	1	SFA
83	`XOR`	`XOR`	`f`	f = f .XOR. WREG	1	1	N,Z
		`XOR`	`f,WREG`	WREG = f .XOR. WREG	1	1	N,Z
		`XOR`	`#lit10,Wn`	Wd = lit10 .XOR. Wd	1	1	N,Z
		`XOR`	`Wb,Ws,Wd`	Wd = Wb .XOR. Ws	1	1	N,Z
		`XOR`	`Wb,#lit5,Wd`	Wd = Wb .XOR. lit5	1	1	N,Z
84	`ZE`	`ZE`	`Ws,Wnd`	Wnd = Zero-extend Ws	1	1	C,Z,N

Note 1: These instructions are available in dsPIC33EPXXXMC20X/50X and PIC24EPXXXMC20X devices only.

2: Read and Read-Modify-Write (e.g., bit operations and logical operations) on non-CPU SFRs incur an additional instruction cycle.

TABLE 30-24: TIMER2 AND TIMER4 (TYPE B TIMER) EXTERNAL CLOCK TIMING REQUIREMENTS

AC CHARACTERISTICS				**Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated)** Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended				
Param No.	**Symbol**	**Characteristic(1)**		**Min.**	**Typ.**	**Max.**	**Units**	**Conditions**
TB10	TtxH	TxCK High Time	Synchronous mode	Greater of: 20 or (TCY + 20)/N	—	—	ns	Must also meet Parameter TB15, N = prescale value (1, 8, 64, 256)
TB11	TtxL	TxCK Low Time	Synchronous mode	Greater of: 20 or (TCY + 20)/N	—	—	ns	Must also meet Parameter TB15, N = prescale value (1, 8, 64, 256)
TB15	TtxP	TxCK Input Period	Synchronous mode	Greater of: 40 or (2 TCY + 40)/N	—	—	ns	N = prescale value (1, 8, 64, 256)
TB20	TCKEXTMRL	Delay from External TxCK Clock Edge to Timer Increment		0.75 TCY + 40	—	1.75 TCY + 40	ns	

Note 1: These parameters are characterized, but are not tested in manufacturing.

TABLE 30-25: TIMER3 AND TIMER5 (TYPE C TIMER) EXTERNAL CLOCK TIMING REQUIREMENTS

AC CHARACTERISTICS				**Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated)** Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended				
Param No.	**Symbol**	**Characteristic(1)**		**Min.**	**Typ.**	**Max.**	**Units**	**Conditions**
TC10	TtxH	TxCK High Time	Synchronous	TCY + 20	—	—	ns	Must also meet Parameter TC15
TC11	TtxL	TxCK Low Time	Synchronous	TCY + 20	—	—	ns	Must also meet Parameter TC15
TC15	TtxP	TxCK Input Period	Synchronous, with prescaler	2 TCY + 40	—	—	ns	N = prescale value (1, 8, 64, 256)
TC20	TCKEXTMRL	Delay from External TxCK Clock Edge to Timer Increment		0.75 TCY + 40	—	1.75 TCY + 40	ns	

Note 1: These parameters are characterized, but are not tested in manufacturing.

TABLE 30-39: SPI2 SLAVE MODE (FULL-DUPLEX, CKE = `0`, CKP = `1`, SMP = `0`) TIMING REQUIREMENTS

AC CHARACTERISTICS			Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ T_A ≤ +85°C for Industrial -40°C ≤ T_A ≤ +125°C for Extended				
Param.	**Symbol**	**Characteristic[1]**	**Min.**	**Typ.[2]**	**Max.**	**Units**	**Conditions**
SP70	FscP	Maximum SCK2 Input Frequency	—	—	15	MHz	**(Note 3)**
SP72	TscF	SCK2 Input Fall Time	—	—	—	ns	See Parameter DO32 **(Note 4)**
SP73	TscR	SCK2 Input Rise Time	—	—	—	ns	See Parameter DO31 **(Note 4)**
SP30	TdoF	SDO2 Data Output Fall Time	—	—	—	ns	See Parameter DO32 **(Note 4)**
SP31	TdoR	SDO2 Data Output Rise Time	—	—	—	ns	See Parameter DO31 **(Note 4)**
SP35	TscH2doV, TscL2doV	SDO2 Data Output Valid after SCK2 Edge	—	6	20	ns	
SP36	TdoV2scH, TdoV2scL	SDO2 Data Output Setup to First SCK2 Edge	30	—	—	ns	
SP40	TdiV2scH, TdiV2scL	Setup Time of SDI2 Data Input to SCK2 Edge	30	—	—	ns	
SP41	TscH2diL, TscL2diL	Hold Time of SDI2 Data Input to SCK2 Edge	30	—	—	ns	
SP50	TssL2scH, TssL2scL	$\overline{\text{SS2}}$ ↓ to SCK2 ↑ or SCK2 ↓ Input	120	—	—	ns	
SP51	TssH2doZ	$\overline{\text{SS2}}$ ↑ to SDO2 Output High-Impedance	10	—	50	ns	**(Note 4)**
SP52	TscH2ssH TscL2ssH	$\overline{\text{SS2}}$ ↑ after SCK2 Edge	1.5 TCY + 40	—	—	ns	**(Note 4)**

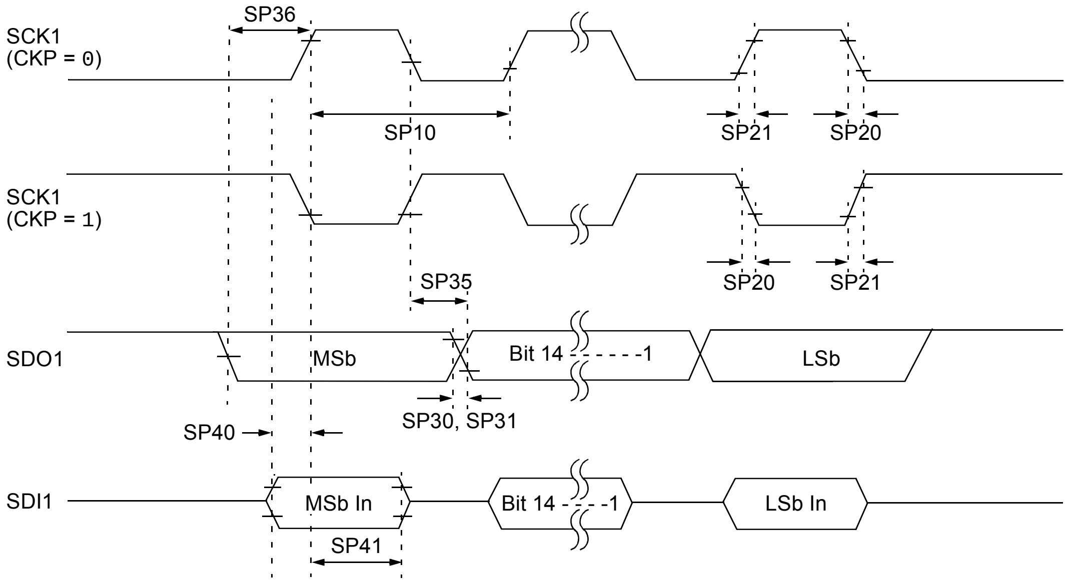
Note 1: These parameters are characterized, but are not tested in manufacturing.

2: Data in “Typical” column is at 3.3V, +25°C unless otherwise stated.

3: The minimum clock period for SCK2 is 66.7 ns. Therefore, the SCK2 clock generated by the master must not violate this specification.

4: Assumes 50 pF load on all SPI2 pins.

FIGURE 30-24: SPI1 MASTER MODE (FULL-DUPLEX, CKE = 1, CKP = x, SMP = 1) TIMING CHARACTERISTICS



Note: Refer to Figure 30-1 for load conditions.

TABLE 30-43: SPI1 MASTER MODE (FULL-DUPLEX, CKE = 1, CKP = x, SMP = 1) TIMING REQUIREMENTS

AC CHARACTERISTICS			**Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated)** Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended				
Param.	**Symbol**	**Characteristic[1]**	**Min.**	**Typ.[2]**	**Max.**	**Units**	**Conditions**
SP10	FscP	Maximum SCK1 Frequency	—	—	10	MHz	**(Note 3)**
SP20	TscF	SCK1 Output Fall Time	—	—	—	ns	See Parameter DO32 **(Note 4)**
SP21	TscR	SCK1 Output Rise Time	—	—	—	ns	See Parameter DO31 **(Note 4)**
SP30	TdoF	SDO1 Data Output Fall Time	—	—	—	ns	See Parameter DO32 **(Note 4)**
SP31	TdoR	SDO1 Data Output Rise Time	—	—	—	ns	See Parameter DO31 **(Note 4)**
SP35	TscH2doV, TscL2doV	SDO1 Data Output Valid after SCK1 Edge	—	6	20	ns	
SP36	TdoV2sc, TdoV2scL	SDO1 Data Output Setup to First SCK1 Edge	30	—	—	ns	
SP40	TdiV2scH, TdiV2scL	Setup Time of SDI1 Data Input to SCK1 Edge	30	—	—	ns	
SP41	TscH2diL, TscL2diL	Hold Time of SDI1 Data Input to SCK1 Edge	30	—	—	ns	

Note 1: These parameters are characterized, but are not tested in manufacturing.

2: Data in “Typical” column is at 3.3V, +25°C unless otherwise stated.

3: The minimum clock period for SCK1 is 100 ns. The clock generated in Master mode must not violate this specification.

4: Assumes 50 pF load on all SPI1 pins.

TABLE 30-46: SPI1 SLAVE MODE (FULL-DUPLEX, CKE = `1`, CKP = `1`, SMP = `0`) TIMING REQUIREMENTS

AC CHARACTERISTICS			**Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated)** Operating temperature -40°C ≤ T_A ≤ +85°C for Industrial -40°C ≤ T_A ≤ +125°C for Extended				
Param.	**Symbol**	**Characteristic[1]**	**Min.**	**Typ.[2]**	**Max.**	**Units**	**Conditions**
SP70	FscP	Maximum SCK1 Input Frequency	—	—	Lesser of F_P or 11	MHz	**(Note 3)**
SP72	TscF	SCK1 Input Fall Time	—	—	—	ns	See Parameter DO32 **(Note 4)**
SP73	TscR	SCK1 Input Rise Time	—	—	—	ns	See Parameter DO31 **(Note 4)**
SP30	TdoF	SDO1 Data Output Fall Time	—	—	—	ns	See Parameter DO32 **(Note 4)**
SP31	TdoR	SDO1 Data Output Rise Time	—	—	—	ns	See Parameter DO31 **(Note 4)**
SP35	TscH2doV, TscL2doV	SDO1 Data Output Valid after SCK1 Edge	—	6	20	ns	
SP36	TdoV2scH, TdoV2scL	SDO1 Data Output Setup to First SCK1 Edge	30	—	—	ns	
SP40	TdiV2scH, TdiV2scL	Setup Time of SDI1 Data Input to SCK1 Edge	30	—	—	ns	
SP41	TscH2diL, TscL2diL	Hold Time of SDI1 Data Input to SCK1 Edge	30	—	—	ns	
SP50	TssL2scH, TssL2scL	$\overline{\text{SS1}}$ ↓ to SCK1 ↑ or SCK1 ↓ Input	120	—	—	ns	
SP51	TssH2doZ	$\overline{\text{SS1}}$ ↑ to SDO1 Output High-Impedance	10	—	50	ns	**(Note 4)**
SP52	TscH2ssH, TscL2ssH	$\overline{\text{SS1}}$ ↑ after SCK1 Edge	1.5 T_{CY} + 40	—	—	ns	**(Note 4)**
SP60	TssL2doV	SDO1 Data Output Valid after $\overline{\text{SS1}}$ Edge	—	—	50	ns	

Note 1: These parameters are characterized, but are not tested in manufacturing.

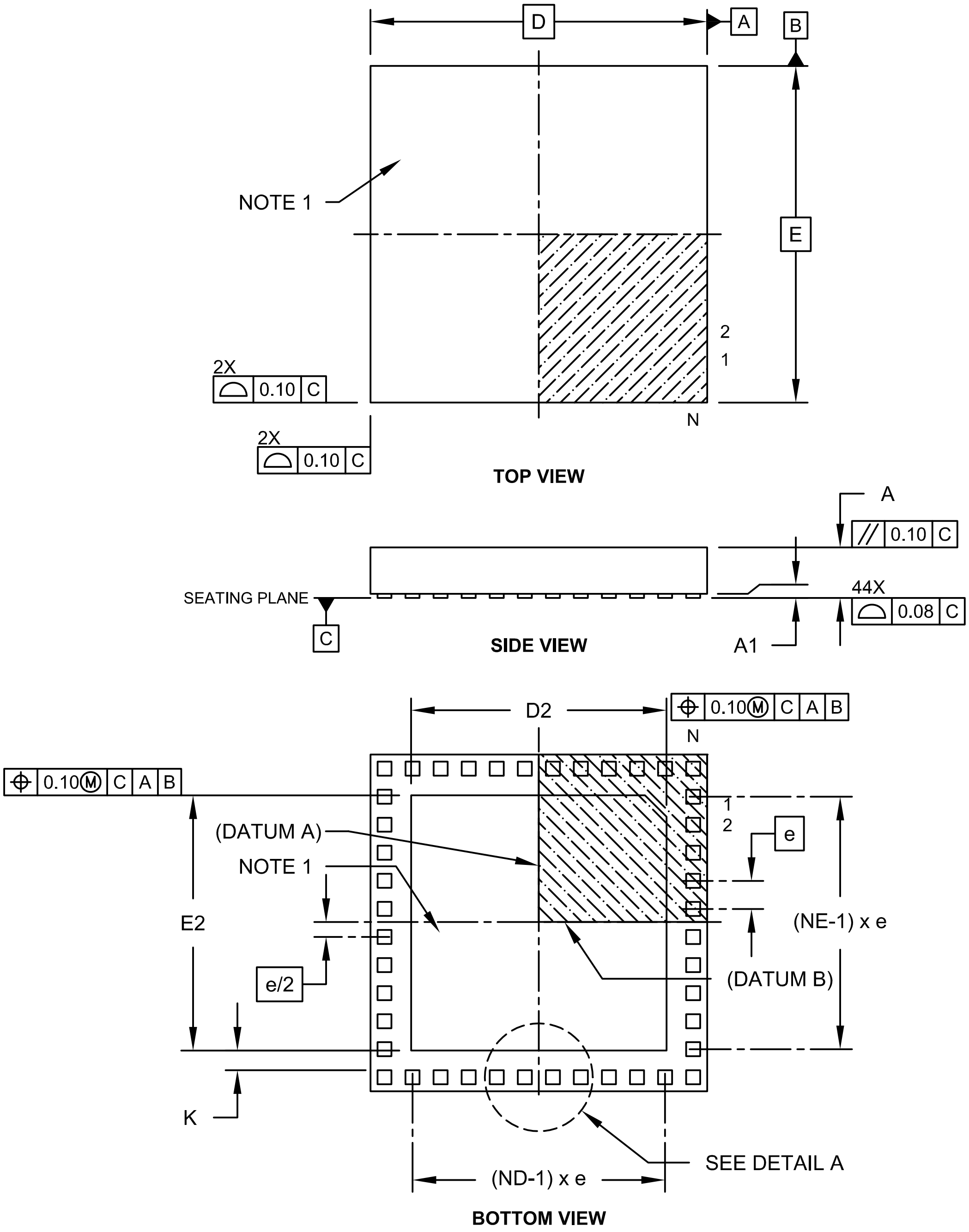
2: Data in “Typical” column is at 3.3V, +25°C unless otherwise stated.

3: The minimum clock period for SCK1 is 91 ns. Therefore, the SCK1 clock generated by the master must not violate this specification.

4: Assumes 50 pF load on all SPI1 pins.

44-Terminal Very Thin Leadless Array Package (TL) – 6x6x0.9 mm Body With Exposed Pad [VTLA]

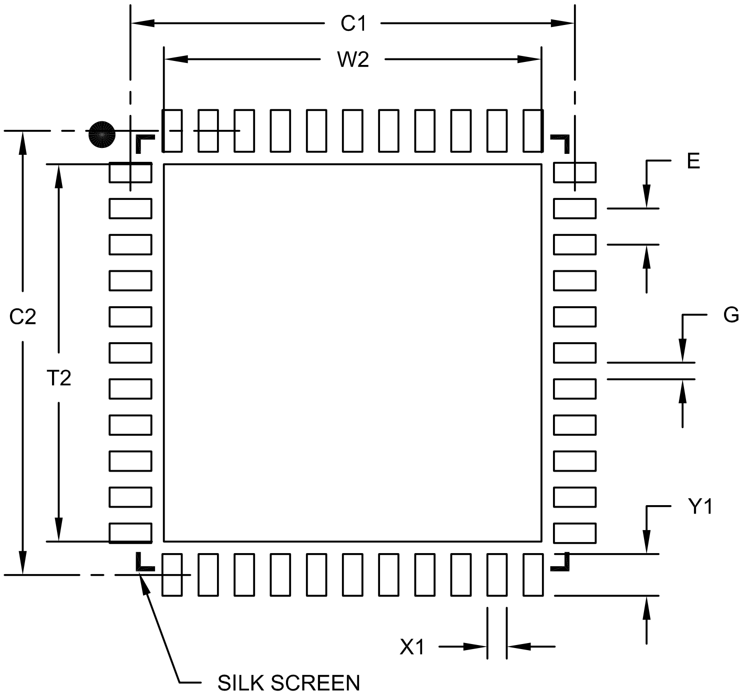
Note:	For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



Microchip Technology Drawing C04-157C Sheet 1 of 2

44-Lead Plastic Quad Flat, No Lead Package (ML) - 8x8 mm Body [QFN]

Note:	For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



RECOMMENDED LAND PATTERN

Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Contact Pitch	E	0.65 BSC		
Optional Center Pad Width	W2			6.60
Optional Center Pad Length	T2			6.60
Contact Pad Spacing	C1		8.00	
Contact Pad Spacing	C2		8.00	
Contact Pad Width (X44)	X1			0.35
Contact Pad Length (X44)	Y1			0.85
Distance Between Pads	G	0.25		

Notes:

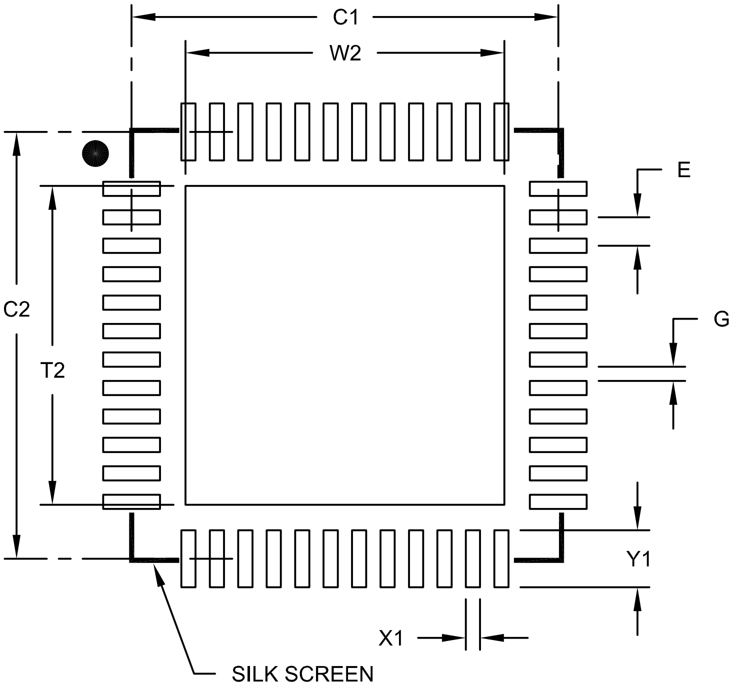
1. Dimensioning and tolerancing per ASME Y14.5M

BSC: Basic Dimension. Theoretically exact value shown without tolerances.

Microchip Technology Drawing No. C04-2103B

48-Lead Ultra Thin Plastic Quad Flat, No Lead Package (MV) - 6x6 mm Body [UQFN] With 0.40 mm Contact Length

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



RECOMMENDED LAND PATTERN

Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Contact Pitch	E	0.40 BSC		
Optional Center Pad Width	W2			4.45
Optional Center Pad Length	T2			4.45
Contact Pad Spacing	C1		6.00	
Contact Pad Spacing	C2		6.00	
Contact Pad Width (X28)	X1			0.20
Contact Pad Length (X28)	Y1			0.80
Distance Between Pads	G	0.20		

Notes:

1. Dimensioning and tolerancing per ASME Y14.5M

BSC: Basic Dimension. Theoretically exact value shown without tolerances.

Microchip Technology Drawing No. C04-2153A